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TLP172GAM

1. Applications

- Battery Management System (BMS) (Non-Automotive)
- Factory Automation (FA)
- Security Systems
- Measuring Instruments
- Smart Meters
- Mechanical relay replacements

2. General

The Toshiba TLP172GAM consists of an infrared LED optically coupled to a photo-MOSFET in a 4-pin SO6 package, which is suitable for surface mount assembly.

The TLP172GAM is suitable for the battery management systems which require space savings.

3. Features

(1) Halogen-free

For details, see "Devices in Halogen-Free Resin Packages" at the end of this datasheet.

(2) Operating temperature range: 110 °C (max)

(3) Normally opened (1-Form-A)

(4) OFF-state output terminal voltage: 400 V (min)

(5) Trigger LED current: 3 mA (max)

(6) ON-state current: 110 mA (max)

(7) ON-state resistance: 45 Ω (max, t < 1 s)

ON-state resistance: 65 Ω (max, continuous)

(8) Isolation voltage: 3750 Vrms (min)

(9) Safety standards

UL-recognized: UL 1577, File No.E67349

cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN 60747-5-5 **(Note 1)**

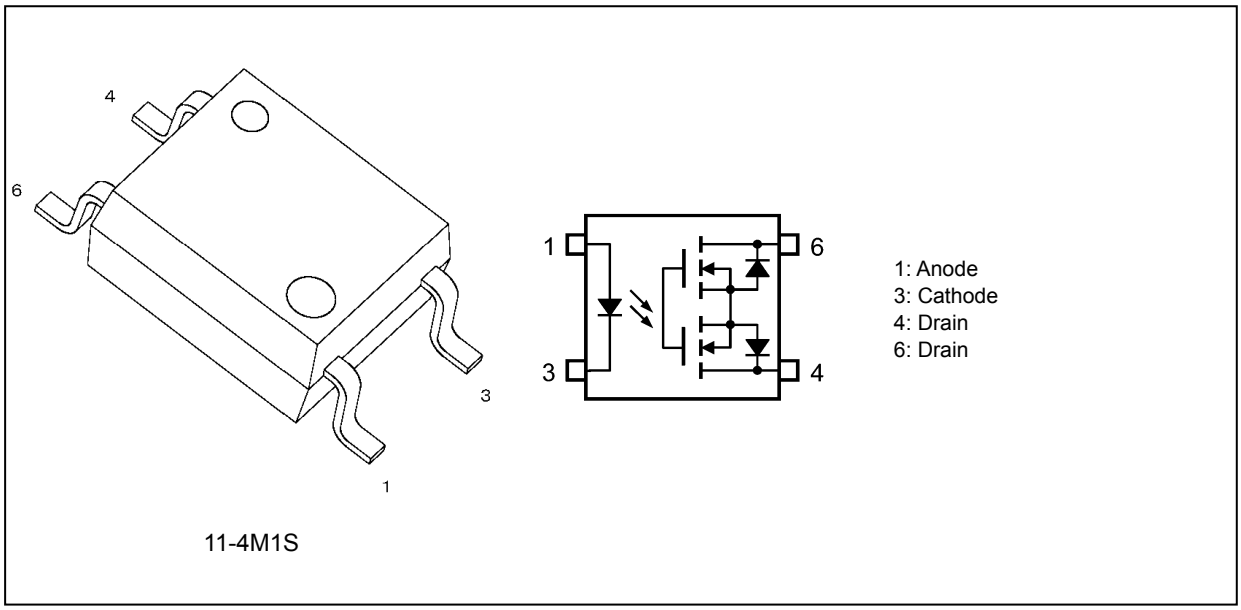
Note 1: When a VDE approved type is needed, please designate the **Option (V4)**.

Table 3.1 Mechanical Parameters

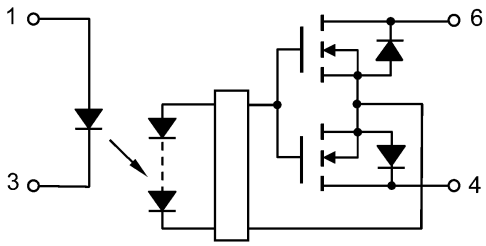
Characteristics	TLP172GAM	Unit
Creepage distances	5.0 (min)	mm
Clearance distances	5.0 (min)	
Internal isolation thickness	0.2 (min)	

Start of commercial production
2018-04

4. Packaging and Pin Assignment



5. Internal Circuit



6. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I_F		30	mA
	Input forward current derating	($T_a \geq$ 25 °C)	$\Delta I_F/\Delta T_a$		-0.3	mA/°C
	Input forward current (pulsed)	(100 μs pulse, 100 pps)	I_{FP}		1	A
	Input reverse voltage		V_R		6	V
	Input power dissipation		P_D		50	mW
	Input power dissipation derating	($T_a \geq$ 25 °C)	$\Delta P_D/\Delta T_a$		-0.5	mW/°C
	Junction temperature		T_j		125	°C
Detector	OFF-state output terminal voltage		V_{OFF}		400	V
	ON-state current		I_{ON}		110	mA
	ON-state current derating	($T_a \geq$ 25 °C)	$\Delta I_{ON}/\Delta T_a$		-1.1	mA/°C
	ON-state current (pulsed)	(t = 100 ms, duty = 1/10)	I_{ONP}		0.33	A
	Output power dissipation		P_O		300	mW
	Output power dissipation derating	($T_a \geq$ 25 °C)	$\Delta P_O/\Delta T_a$		-3.0	mW/°C
	Junction temperature		T_j		125	°C
Common	Storage temperature		T_{stg}		-55 to 125	
	Operating temperature		T_{opr}		-40 to 110	
	Lead soldering temperature	(10 s)	T_{sol}		260	
	Isolation voltage	(AC, 60 s, R.H. ≤ 60 %)	BV_S	(Note 1)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

7. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
Supply voltage	V_{DD}		—	—	320	V
Input forward current	I_F		5	7.5	25	mA
ON-state current	I_{ON}		—	—	110	
Operating temperature	T_{opr}		-40	—	100	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

8. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V_F		I_F = 10 mA	1.1	1.27	1.4	V
	Input reverse current	I_R		V_R = 5 V	—	—	10	μA
	Input capacitance	C_t		V = 0 V, f = 1 MHz	—	30	—	pF
Detector	OFF-state current	I_{OFF}		V_{OFF} = 400 V	—	0.001	1	μA
	Output capacitance	C_{OFF}		V = 0 V, f = 1 MHz	—	30	—	pF

9. Coupled Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Trigger LED current	I_{FT}		I_{ON} = 110 mA	—	0.8	3	mA
Return LED current	I_{FC}		I_{OFF} = 100 μA	0.1	0.5	—	mA
ON-state resistance	R_{ON}		I_{ON} = 110 mA, I_F = 5 mA, t < 1 s	—	30	45	Ω
			I_{ON} = 110 mA, I_F = 5 mA	—	40	65	

10. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	V_S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	V_S = 500 V, R.H. ≤ 60 %	5×10^{10}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	3750	—	—	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

11. Switching Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Turn-on time	t_{ON}		See Fig. 11.1 R_L = 200 Ω, V_{DD} = 20 V, I_F = 5 mA	—	0.5	1	ms
Turn-off time	t_{OFF}			—	0.1	0.5	

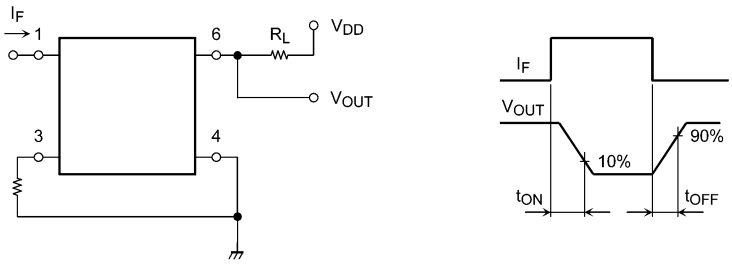


Fig. 11.1 Switching Time Test Circuit and Waveform

12. Characteristics Curves and Circuit Connections

12.1. Characteristics Curves (Note)

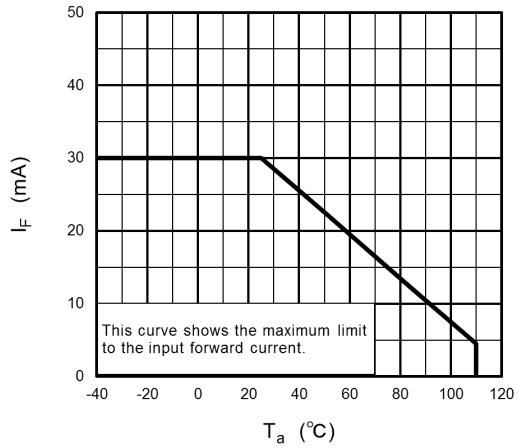


Fig. 12.1.1 I_F - T_a

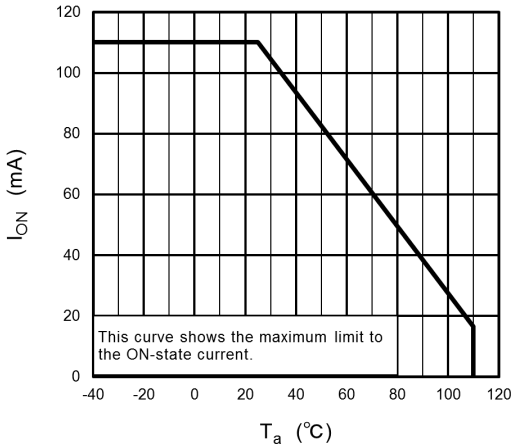


Fig. 12.1.2 I_{ON} - T_a

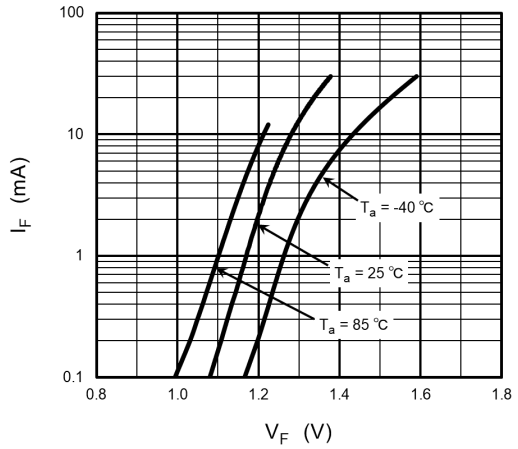


Fig. 12.1.3 I_F - V_F

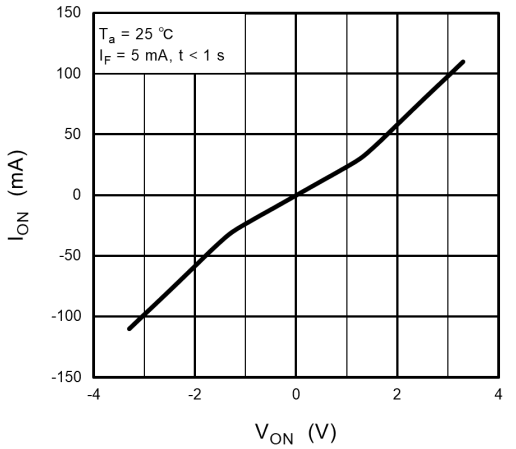


Fig. 12.1.4 I_{ON} - V_{ON}

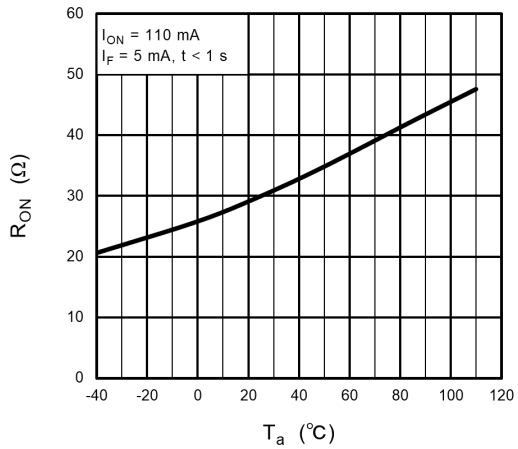


Fig. 12.1.5 R_{ON} - T_a

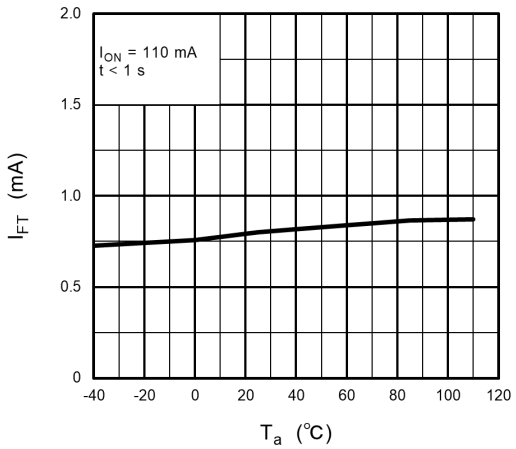


Fig. 12.1.6 I_{FT} - T_a

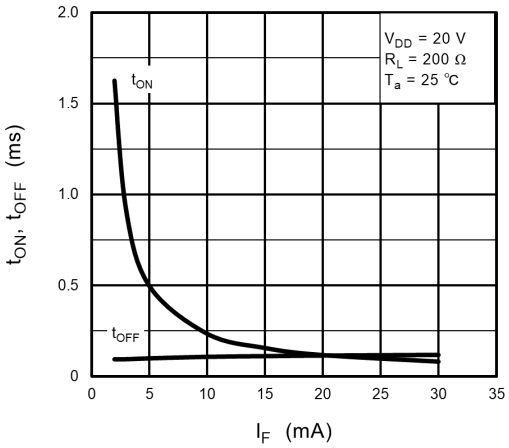


Fig. 12.1.7 t_{ON}, t_{OFF} - I_F

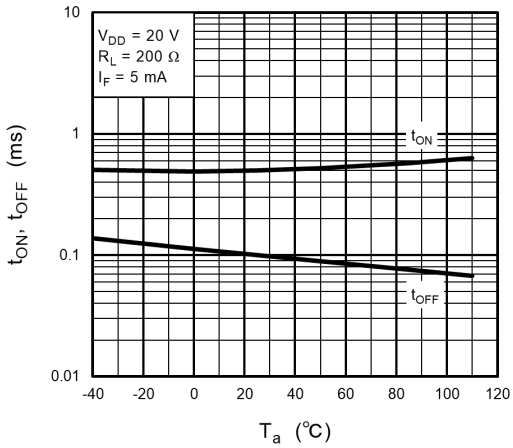


Fig. 12.1.8 t_{ON}, t_{OFF} - T_a

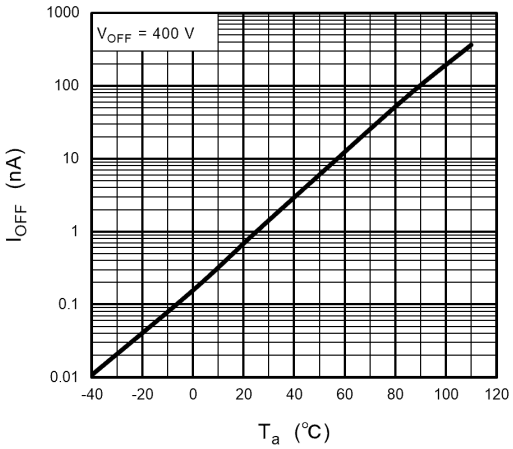


Fig. 12.1.9 I_{OFF} - T_a

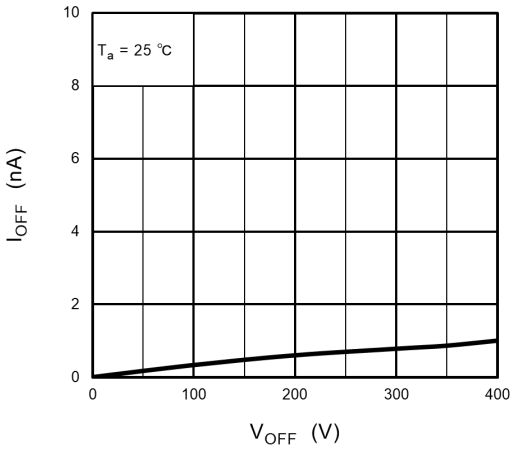


Fig. 12.1.10 I_{OFF} - V_{OFF}

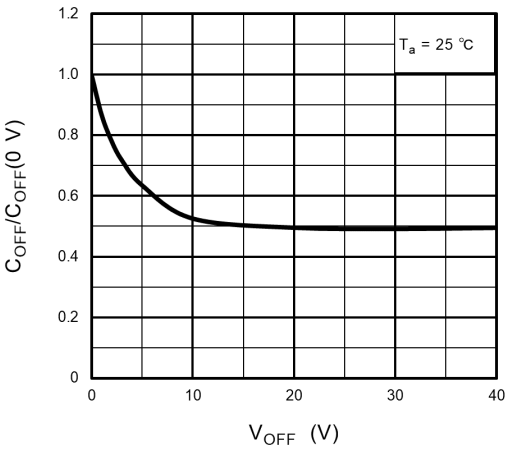


Fig. 12.1.11 C_{OFF}/C_{OFF}(0 V) - V_{OFF}

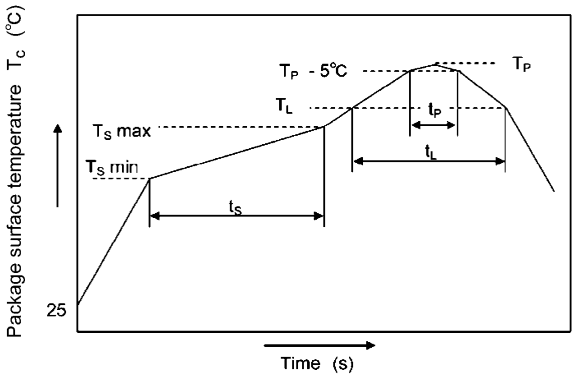
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.
  The soldering temperature profile is based on the package surface temperature.
  (See the figure shown below, which is based on the package surface temperature.)
  Reflow soldering must be performed once or twice.
  The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	T_S	150	200	°C
Preheat time	t_S	60	120	s
Ramp-up rate (T_L to T_P)			3	°C/s
Liquidus temperature	T_L	217		°C
Time above T_L	t_L	60	150	s
Peak temperature	T_P		260	°C
Time during which T_c is between (T_P – 5) and T_P	t_P		30	s
Ramp-down rate (T_P to T_L)			6	°C/s

An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow
  Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
  Mounting condition of 260 °C within 10 seconds is recommended.
  Flow soldering must be performed once.
- When using soldering Iron
  Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
  Heating by soldering iron must be done only once per lead.

13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Ordering Information (Example of Item Name)

Item Name	Packaging (Note 1)	VDE Option	Packing (MOQ)
TLP172GAM(E	SMD		Magazine (125 pcs)
TLP172GAM(TPL,E	SMD		Tape and reel (3000 pcs)
TLP172GAM(TPR,E	SMD		Tape and reel (3000 pcs)
TLP172GAM(V4,E	SMD	EN 60747-5-5	Magazine (125 pcs)
TLP172GAM(V4TL,E	SMD	EN 60747-5-5	Tape and reel (3000 pcs)
TLP172GAM(V4TR,E	SMD	EN 60747-5-5	Tape and reel (3000 pcs)

Note 1: SMD: Surface Mount Device

15. Devices in Halogen-Free Resin Packages

・This product is Halogen-Free

Toshiba Electronic Devices & Storage Corporation ("Toshiba") defines a "Halogen-Free resin semiconductor product" as a semiconductor product in which:

(1) the encapsulating resins do not contain any of the following elements: bromine (Br), chlorine (Cl) and antimony (Sb), respectively, in an amount exceeding 0.09 weight percent, and do not contain chlorine and bromine in an aggregate amount exceeding 0.15 weight percent of the encapsulating resins, and/or

(2) the resin portion(s) in printed circuit boards do not contain any of the following elements: bromine, chlorine and antimony, respectively, in an amount exceeding 0.09 weight percent, and do not contain chlorine and bromine in an aggregate amount exceeding 0.15 weight percent of the each resin portion(s) in printed circuit boards.

For avoidance of doubt, "Halogen-Free resin semiconductor product" does not mean, and Toshiba does not make any warranty of any kind, that said semiconductor product is entirely free of antimony or of any of the following elements of the halogen family: bromine, chlorine, iodine (I), fluorine (F) and astatine (At).

In addition, a Halogen-Free resin semiconductor product may contain antimony and/or any of the elements of the halogen family as mentioned in the above paragraph in one or more portion(s) of the semiconductor product other than the encapsulating resins and the resin portion(s) in printed circuit boards.

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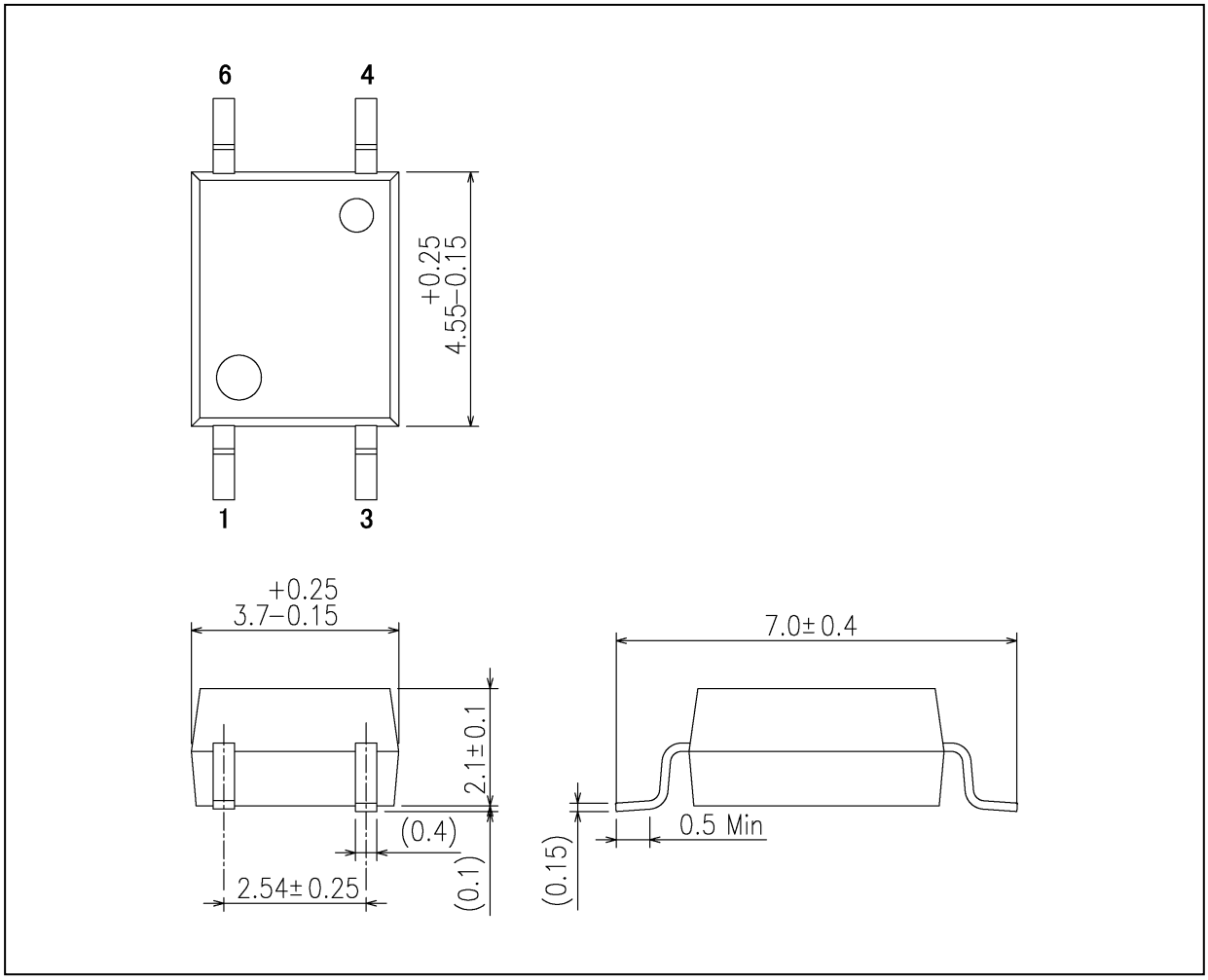
Package Dimensions

Unit: mm



Weight: 0.1 g (typ.)

Package Name(s)
TOSHIBA: 11-4M1S

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